

**PART INFORMATION**

Mfg Item Number	LS1012AXN7KKB
Mfg Item Name	FCLGA 211 9.6*9.6*0.805

**SUPPLIER**

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2018-05-09
Response Document ID	00NGK10949D421A1.2
Contact Name	Freescale Semiconductor Inc
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URL for Additional Information	www.freescale.com

**DECLARATION**

EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	
EU RoHS Exemption(s)	

**MANUFACTURING**

Mfg Item Number	LS1012AXN7KKB
Mfg Item Name	FCLGA 211 9.6*9.6*0.805
Version	ALL
Weight	0.164300
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Die Encapsulant, Halogen-free	0.0896						g				
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.00447444	g	49938	4.9938	27233	2.7233
Die Encapsulant, Halogen-free		Glass	Silicon dioxide	7631-86-9		0.0178976	g	199750	19.975	108932	10.8932
Die Encapsulant, Halogen-free		Glass	Silica, vitreous	60676-86-0		0.06722796	g	750312	75.0312	409186	40.9186
Organic Substrate, Halogen-free	0.0469						g				
Organic Substrate, Halogen-free		Solvents, additives, and other materials	Acrylonitrile/Butadiene copolymer, carboxyl terminated (26/74)	68891-46-3		0.00297899	g	63518	6.3518	18131	1.8131
Organic Substrate, Halogen-free		Metals	Barium sulfate	7727-43-7		0.00547736	g	116786	11.6786	33337	3.3337
Organic Substrate, Halogen-free		Plastics/polymers	4,4'-dihydroxy-3,3',5,5'-tetramethylbiphenyl diglycidyl ether	85954-11-6		0.00499523	g	106508	10.6508	30403	3.0403
Organic Substrate, Halogen-free		Plastics/polymers	Phenolic Polymer Resin, Epikote 155	9003-36-5		0.01871863	g	399118	39.9118	113929	11.3929
Organic Substrate, Halogen-free		Solvents, additives, and other materials	Silicon	7440-21-3		0.00227742	g	48559	4.8559	13861	1.3861
Organic Substrate, Halogen-free		Glass	Fibrous-glass-wool	65997-17-3		0.01245237	g	265509	26.5509	75790	7.579
Solder Paste	0.0082						g				
Solder Paste		Metals	Copper, metal	7440-50-8		0.0000451	g	5500	0.55	274	0.0274
Solder Paste		Metals	Silver, metal	7440-22-4		0.00027059	g	32999	3.2999	1646	0.1646
Solder Paste		Metals	Tin, metal	7440-31-5		0.00788431	g	961501	96.1501	47987	4.7987
Pb-free Bumped Semiconductor D	0.0196						g				
Pb-free Bumped Semiconductor D		Nickel (external applications only)	Nickel	7440-02-0		0.000098	g	5000	0.5	596	0.0596
Pb-free Bumped Semiconductor D		Metals	Silver, metal	7440-22-4		0.00006174	g	3150	0.315	375	0.0375
Pb-free Bumped Semiconductor D		Metals	Tin, metal	7440-31-5		0.00170226	g	86850	8.685	10360	1.036
Pb-free Bumped Semiconductor D		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.0001764	g	9000	0.9	1073	0.1073
Pb-free Bumped Semiconductor D		Glass	Silicon, doped	-		0.0175616	g	896000	89.6	106887	10.6887

## LINKS

MCD LINK	
NXP website	<a href="http://www.nxp.com">http://www.nxp.com</a>
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf</a>
China RoHS	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY</a>
REACH signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf</a>
ELV signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf</a>
Conflict Minerals statement	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf</a>
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX</a>
FAQ	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ</a>
Technical Service Request	<a href="http://www.nxp.com/support/sales-and-support:SUPPORTHOME">http://www.nxp.com/support/sales-and-support:SUPPORTHOME</a>
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	<a href="http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf">http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf</a>

IPC1752 XML LINKS

[http://www.freescale.com/mcdfs/LS1012AXN7KKB\\_IPC1752\\_v11.xml](http://www.freescale.com/mcdfs/LS1012AXN7KKB_IPC1752_v11.xml)

[http://www.freescale.com/mcdfs/LS1012AXN7KKB\\_IPC1752A.xml](http://www.freescale.com/mcdfs/LS1012AXN7KKB_IPC1752A.xml)